



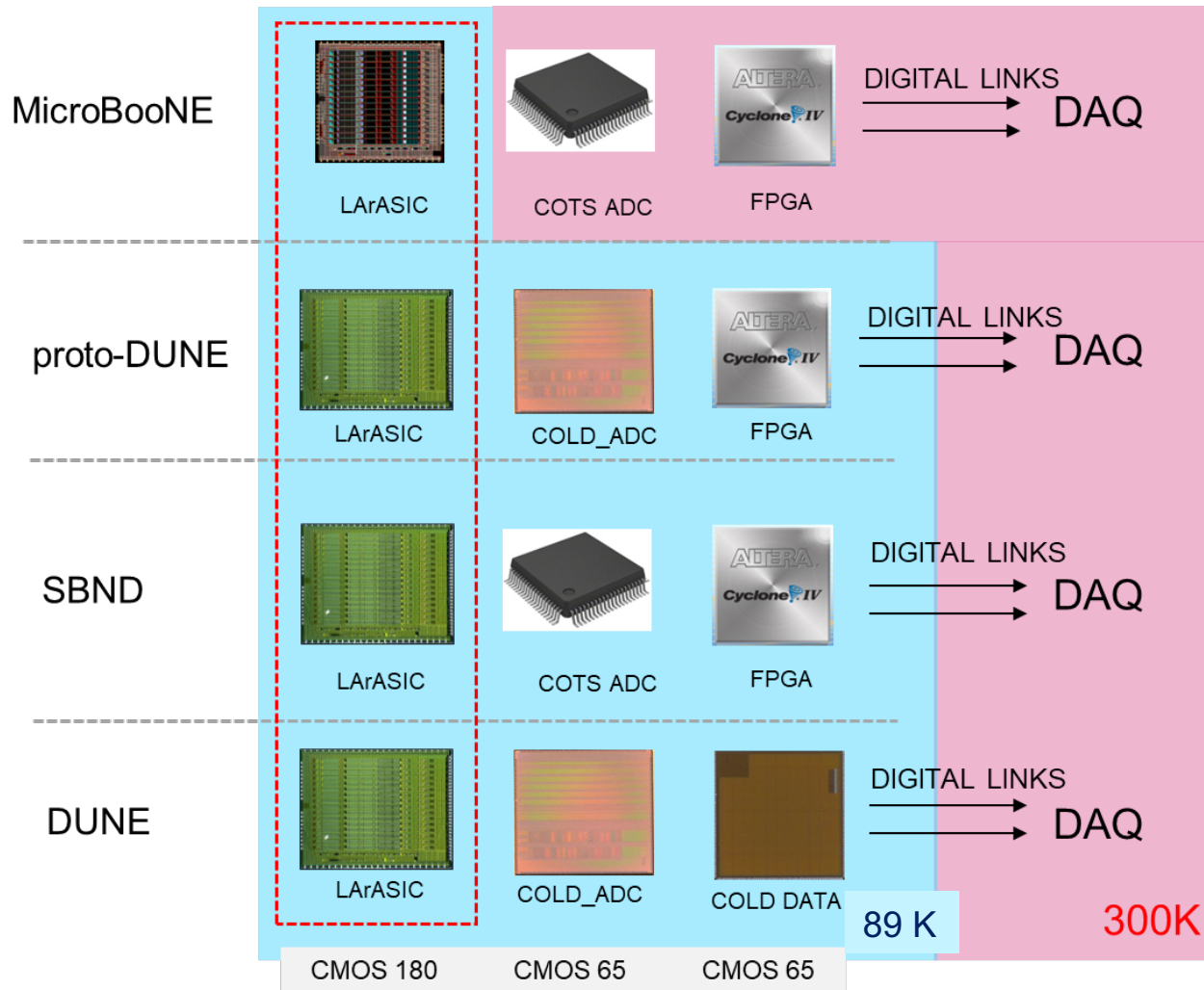
Front-end Application Specific Integrated Circuits (ASICs) in 65 nm CMOS for Charge and Light Readout

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November 8, 2023



Status of Front-end ASICs



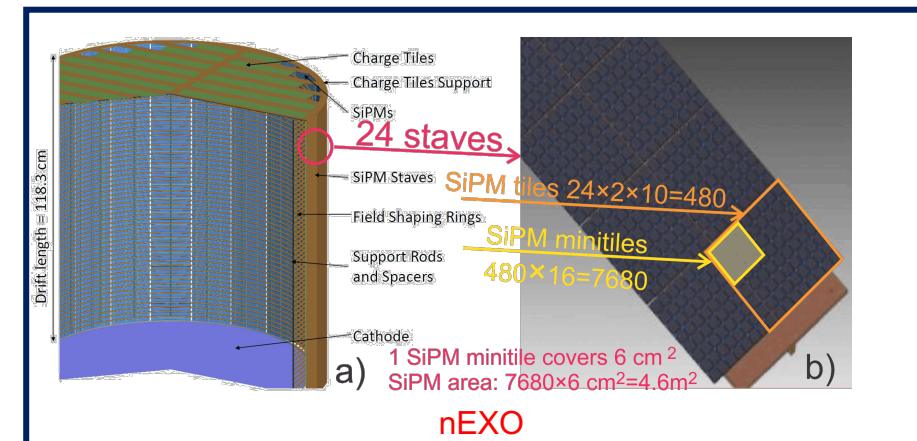
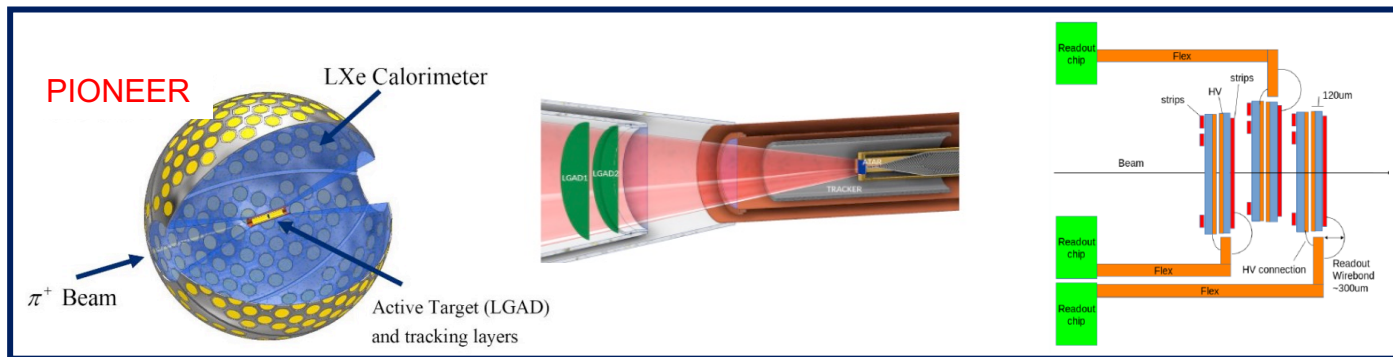
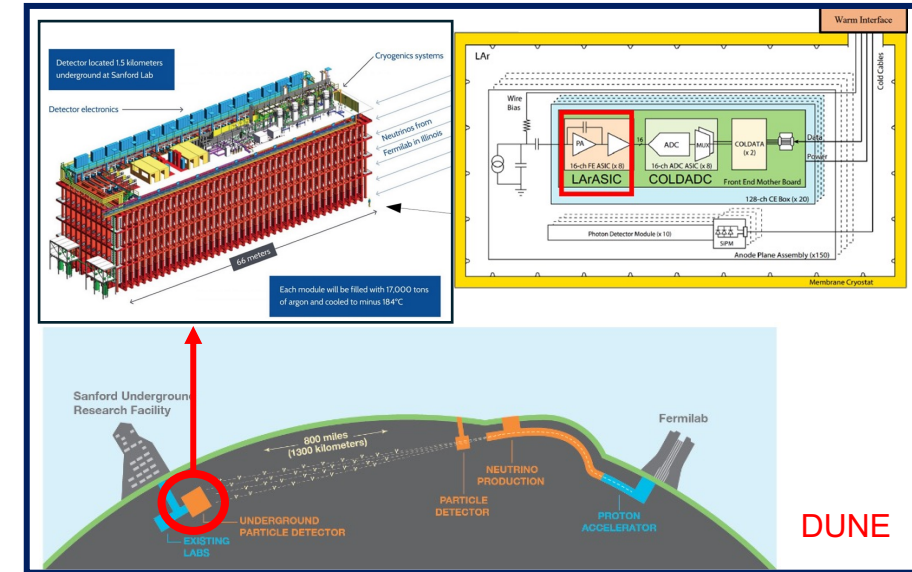
3 ASICs vs. 1 ASIC solution:

- Initially two readout options were proposed:
 - 3 ASICs vs. 1 ASIC (idea of building 1 ASIC, combining FE/ADC/transmission brought in 2016 and included as parallel path of development)
- Evolutionary development MiCroBooNE → DUNE led to the 3 ASIC solution that:
 - Helped perfect the FE (through multiple iterations)
 - Allowed debugging (procedure for ADC calibration)
 - Allowed optimization

Currently in development: **CHAMPS**
 (CHarge AMPlifier + Shaper →
 LArASIC translated to 65 nm +
 additional features)

Targets for CHAMPS

Experiment	Temperature	Detector Capacitance	Shaping Time	Noise	Dynamic Range
DUNE FD 3/4 charge readout	89 K – 300 K	150 pF – 200 pF	250 ns – 2 μ s	500 e ⁻ at 87 K	10 bits
nEXO light readout	160 K – 300 K	5 nF	1 μ s	0.1 pe ⁻ at 160 K	10 bits
PIONEER	160 K – 300 K	20 pF	20 ns	570 e ⁻ at 160 K	10 bits



Planned specifications

LArASIC (P5B)

Technology	180 nm CMOS – 1-poly, 6-metal, MiM cap, sil blk resistors			
Supply Voltage	1.8 V			
Temperature Range	77 – 300 K			
Number of Channels	16			
Max Single-Ended Output Swing	1.4 V peak to peak (0.2 – 1.6 V)			
Gain Selection (mV/fC)	4.7	7.8	14	25
Full-Scale Input Charge (fC)	300	180	100	56
Baseline selection	200 mV (collection mode)		900 mV (induction mode)	
Charge Preamplifier Polarity	Negative (collection mode)		Bipolar (induction mode)	
Adaptive-Reset Current Selection (nA)	0.1	0.5	1	5
Shaper Peaking Time Selection (μs)	0.5	1	2	3
Output Coupling	AC (100 μs HPF time-constant)		DC	
Output Selection	Shaper	SE buffer	SEDC buffer	
Total Channel Settings	1024			
Integrated Test Capacitor	200 fF			
Temperature Sensor	0.8728 V @ 25°C + 2.868 mV/°C			
Integrated Pulse Generator	6-bit DAC based			
Configuration Control	SPI interface with 144 register bits			

CHAMPS250

65 nm CMOS: 1-poly, 9-metal	65 nm CMOS: 1-poly, 9-metal
✓	✓
✓	✓
✓	✓
✓	✓
✓	✓
✓	✓
✓	✓
✓	✓
✓	✓
✓	✓
✓	✓
250 ns – 2 μs	10 ns – 250 ns
✓	✓
✓	✓
TBD	TBD
TBD	TBD
✓	✓
✓	✓
I ² C interface	I ² C interface

CHAMPS10

LArASIC – status

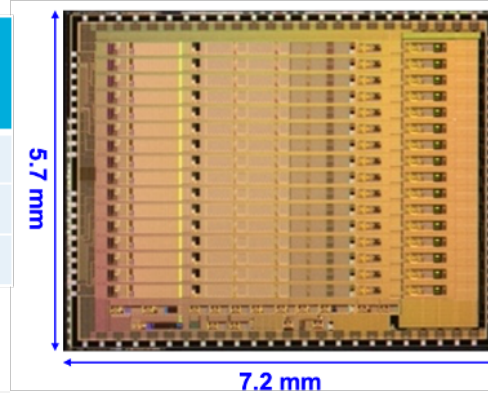
LArASIC MPW met all the DUNE requirements → fabricated ~1800 P5 and 1800 P5B (180 nm) chips (eng. run) for ProtoDUNE II

LArASIC Chips	Temp.	Tested Chips#	Good # (All channels are normal)	Yield
P5	RT	49	49	100 %
P5B	RT	1642	1635*	~99.57 %
P5B	LNT	317	317	100 %

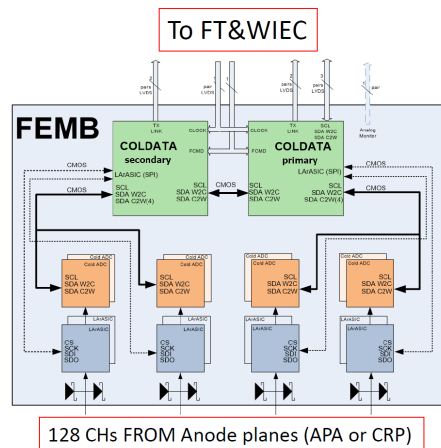
P5B has improved input ESD protection compared to P5

*Only 1 out of 16 channels in each of the two chips are non-functional

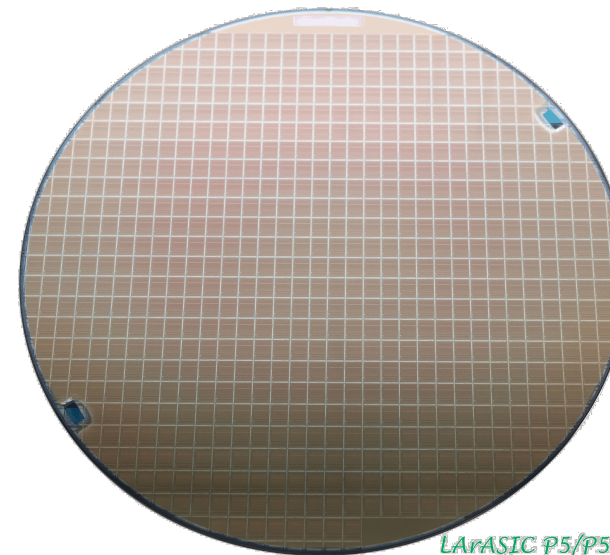
>6 months ago, now more statistics is available



LArASIC performance with differential interface



24 FEMBs arrived at CERN for ProtoDUNE-II installation



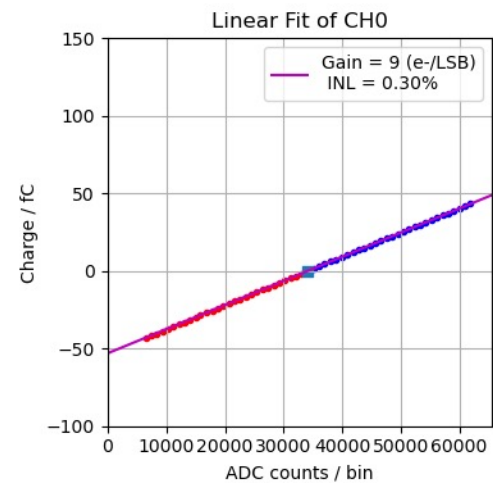
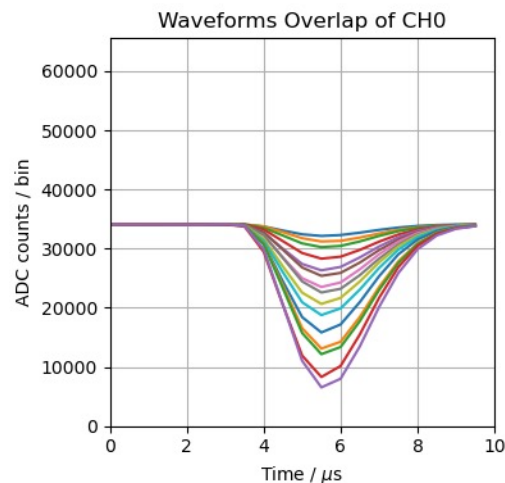
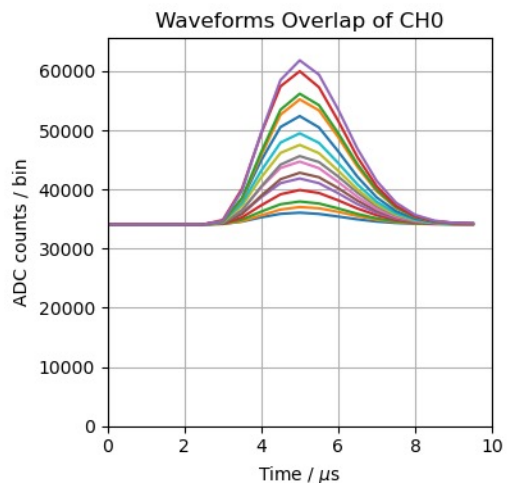
250 wafers LArASIC production run for DUNE 75k P5 and 75k P5B chips

8" wafer with 610 LArASICs P5 and P5A(B) w. increased ESD protection

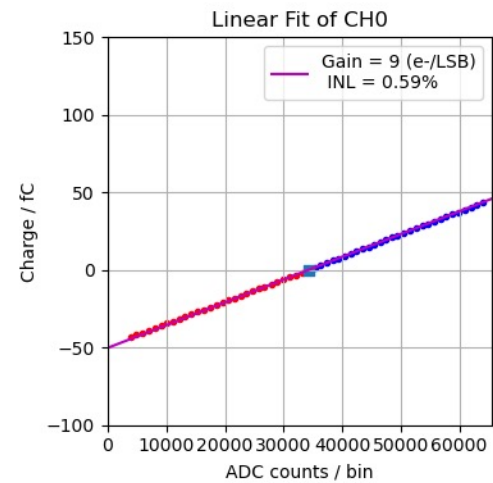
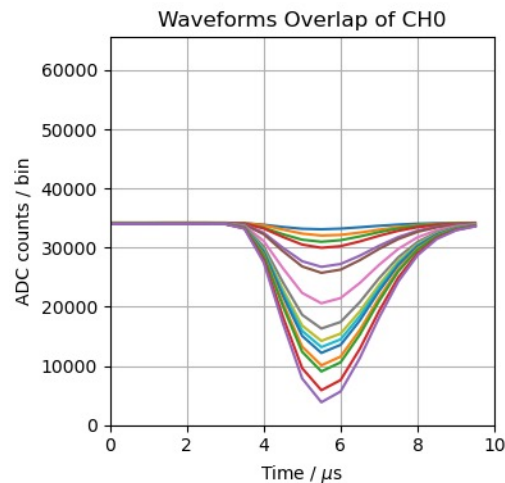
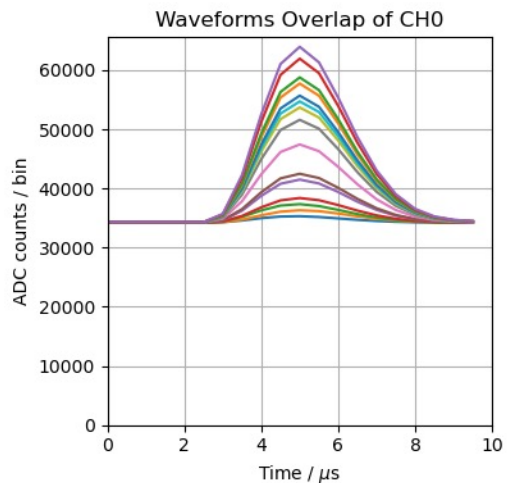
Measured characteristics (LArASIC P5)

Charge gain = 9, 900mV baseline, 500pA, $T_p = 2 \mu\text{s}$, ADC 16-bit mode

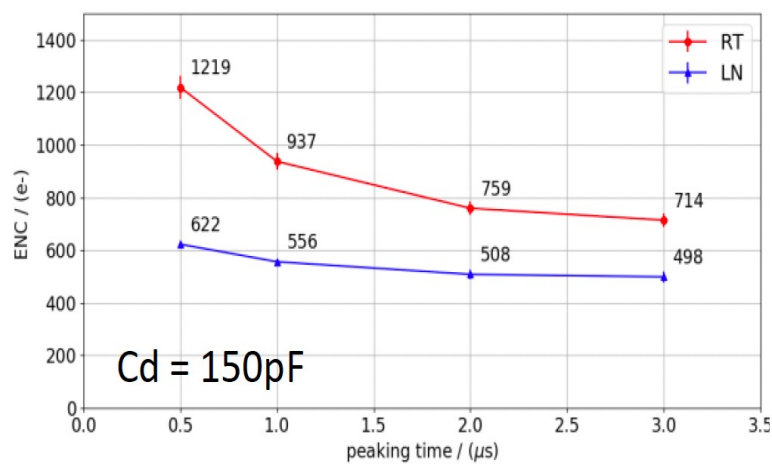
RT



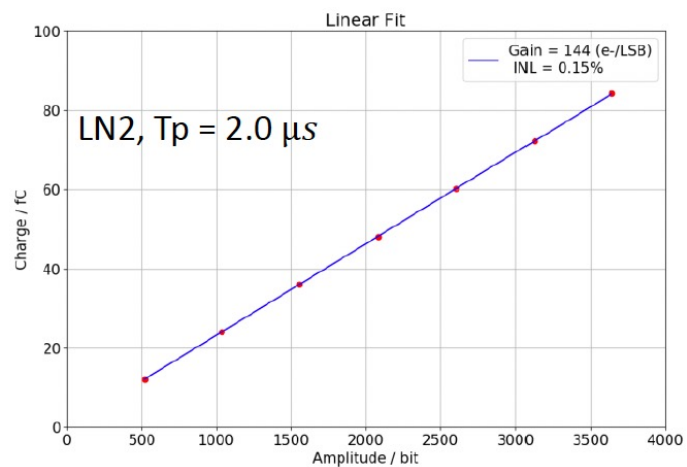
LN2



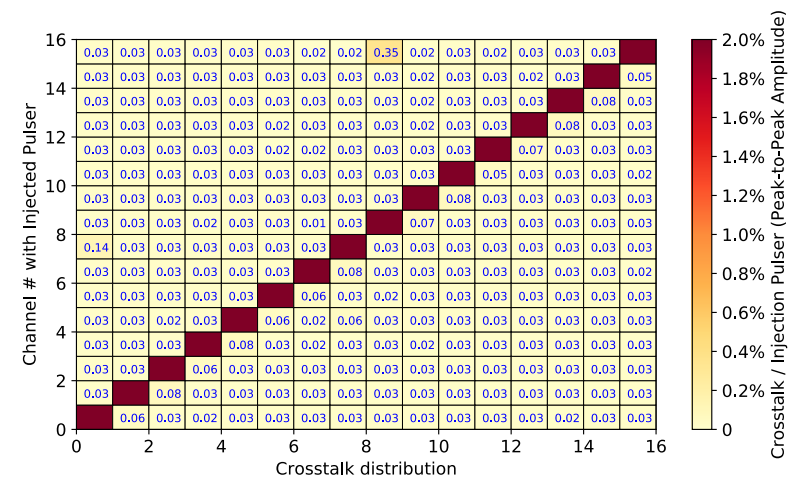
Measured characteristics (LArASIC P5)



Low Noise

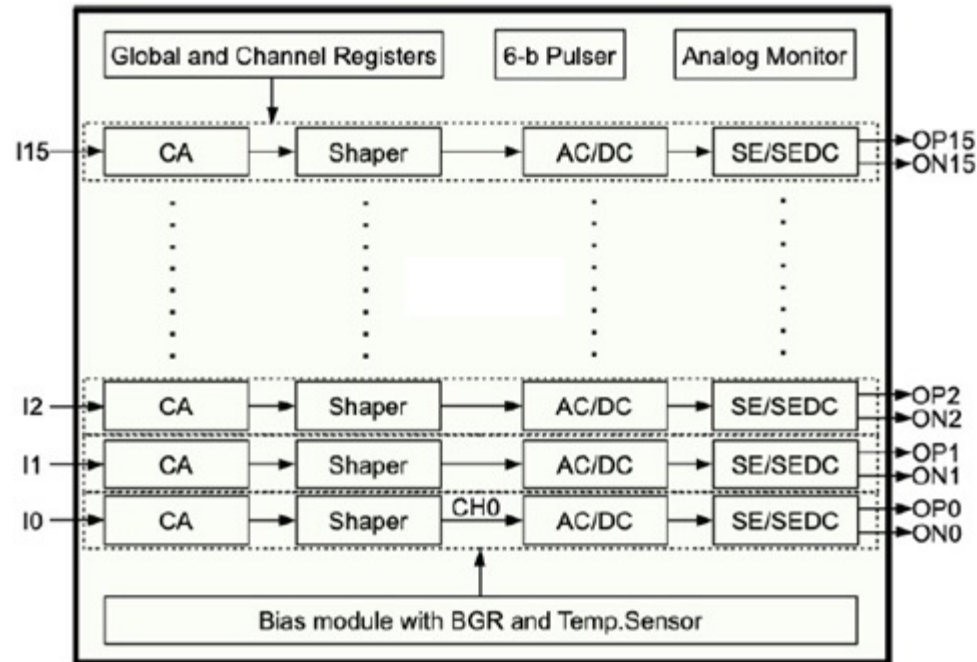
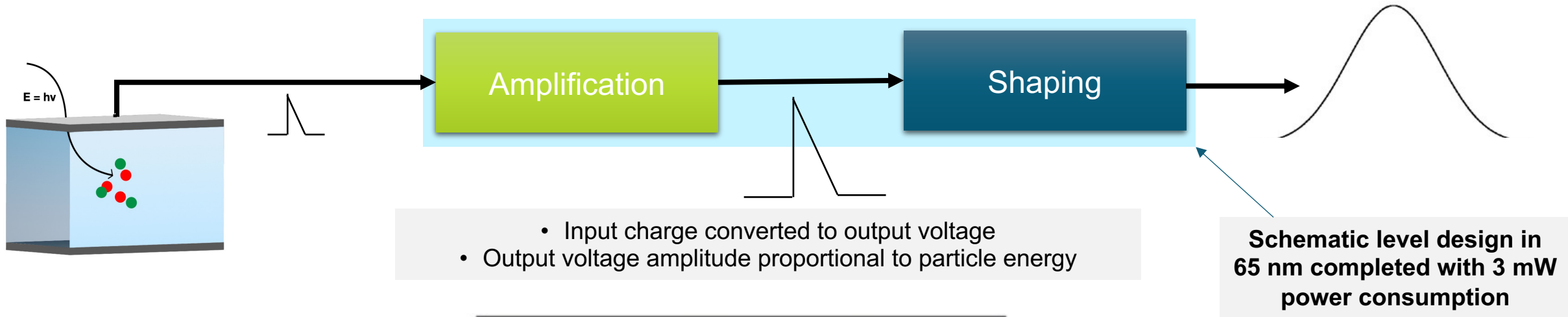


High Linearity

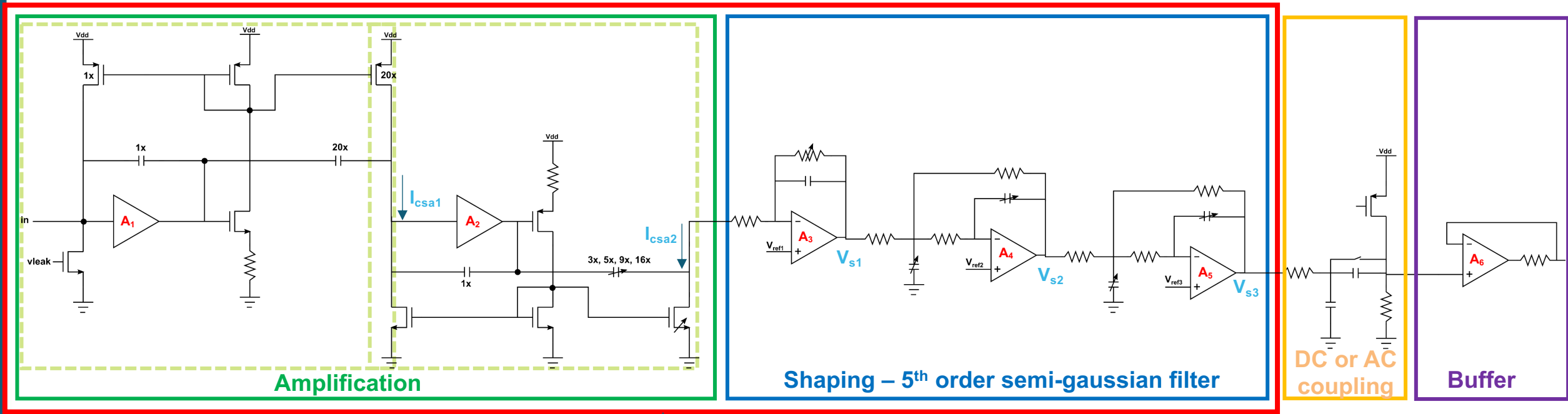


Low Crosstalk

CHAMPS status & overview

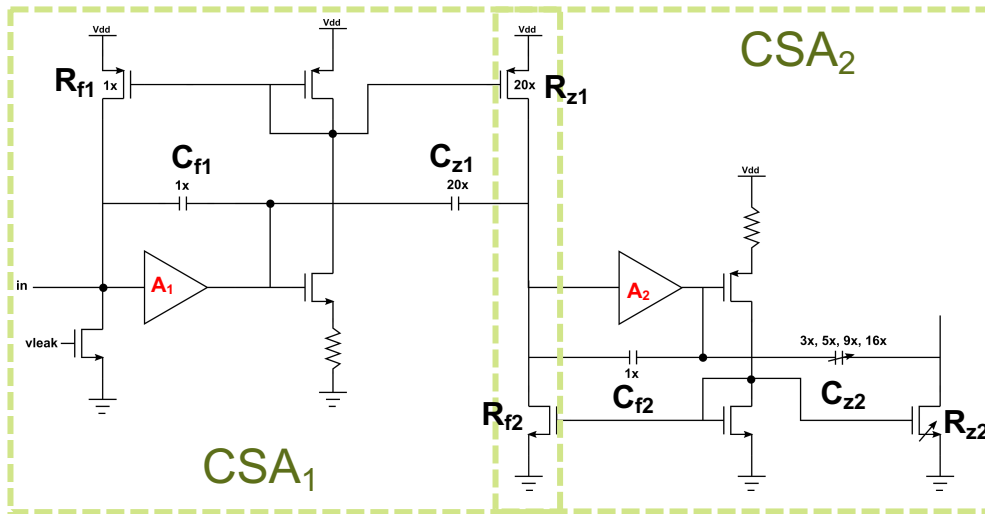


Circuit implementation



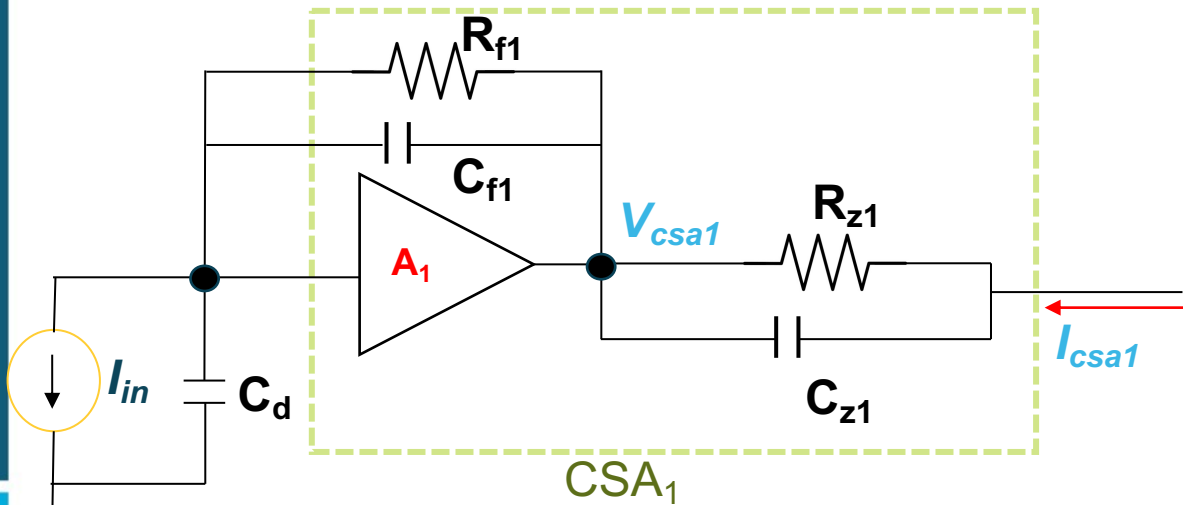
Schematic level design in 65 nm completed with 3 mW power consumption and programmable shaping times of 250 ns, 500 ns, 1 μ s and 2 μ s

Charge Sensitive Amplifier design



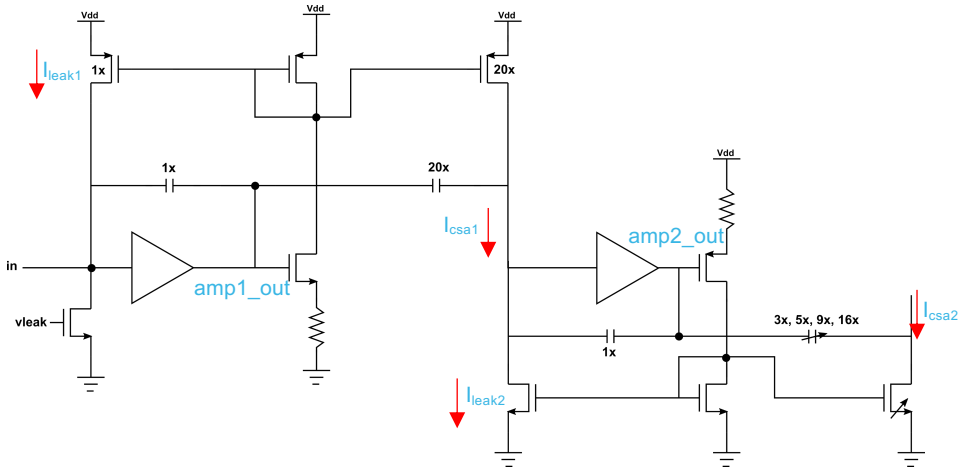
- Charge amplifiers use current-mirror based adaptive continuous reset
- A_1 and A_2 : 3-stage amplifiers (> 100 dB gain each, bandwidths of 10 MHz and 20-50 MHz)
- Pole zero cancellation ($C_f R_f = C_z R_z$) ensures fast I_{csa1} pulse and prevents baseline drift

$$I_{csa1}(s) = I_{in}(s) \underbrace{\frac{R_{f1}}{(1 + sC_{f1}R_{f1})}}_{V_{csa1}} \frac{(1 + sC_{z1}R_{z1})}{R_{z1}}$$



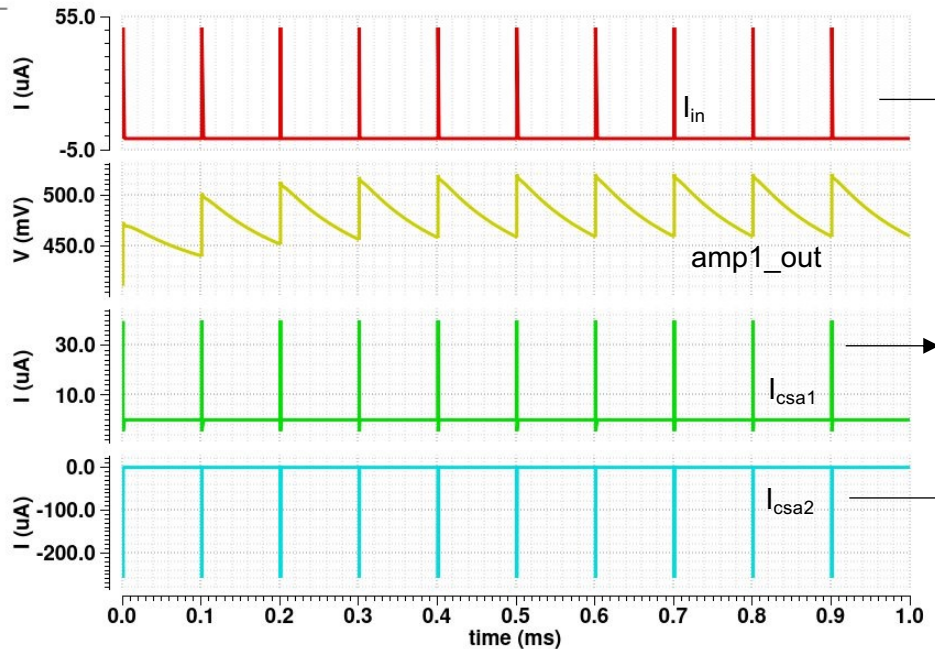
- $C_{z1} = 20C_{f1}$, $R_{z1} = (1/20)R_{f1}$, charge gain provided by $CSA_1 = 20$
- $C_{z1} = (3 \text{ or } 5 \text{ or } 9 \text{ or } 16)C_{f1}$, $R_{z1} = (1/3 \text{ or } 1/5 \text{ or } 1/9 \text{ or } 1/20)R_{f1}$, charge gain (programmable) provided by $CSA_2 = 3 \text{ or } 5 \text{ or } 9 \text{ or } 16$

CSA₁ and CSA₂ charge multiplication check



Transient Response

- Name ...
- /R12/PLUS
- /amp1_out
- /R0/PLUS
- /R1/PLUS



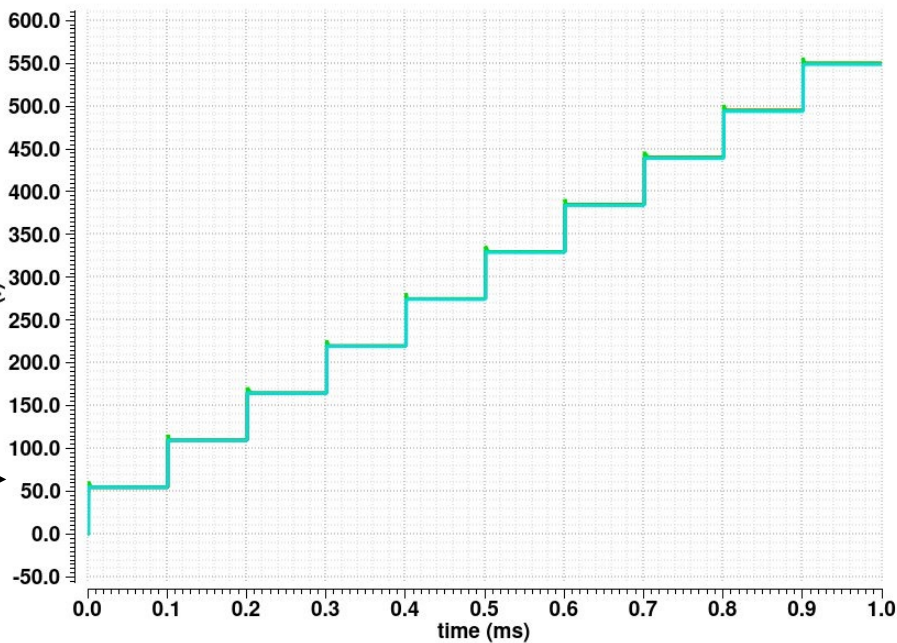
$$\text{input_charge} = \text{output_charge1} / \text{gain1} = \text{output_charge2} / (\text{gain1} * \text{gain2})$$

- Name ...
- input_charge
- output_charge1/gain1
- ...t_charge2/(gain1*gain2)

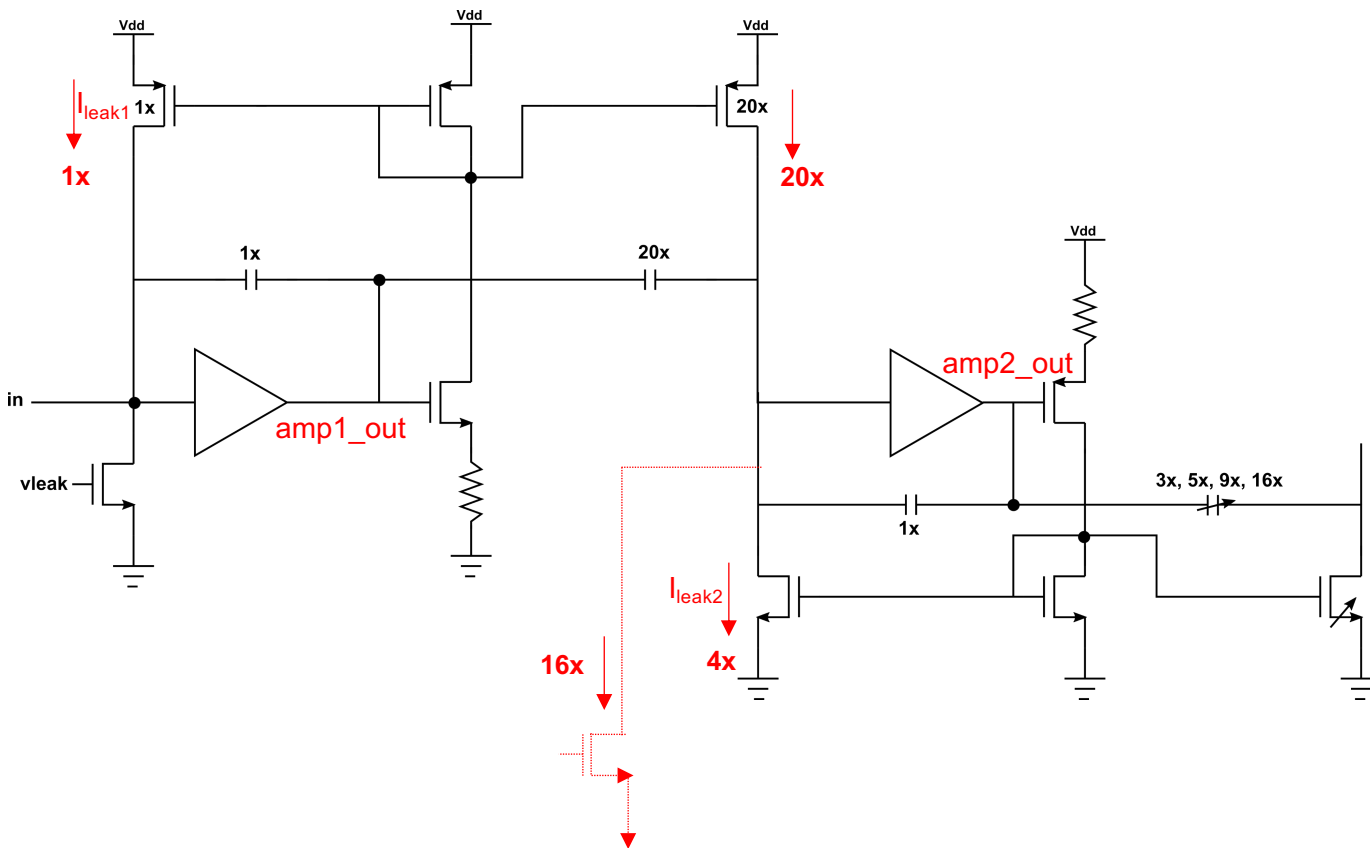
$$\int I_{in} \rightarrow$$

$$\frac{\int (I_{csa1} - 20 I_{leak1})}{20} \rightarrow$$

$$\frac{\int (I_{csa2} - 16 I_{leak2})}{20 \times 16} \rightarrow$$

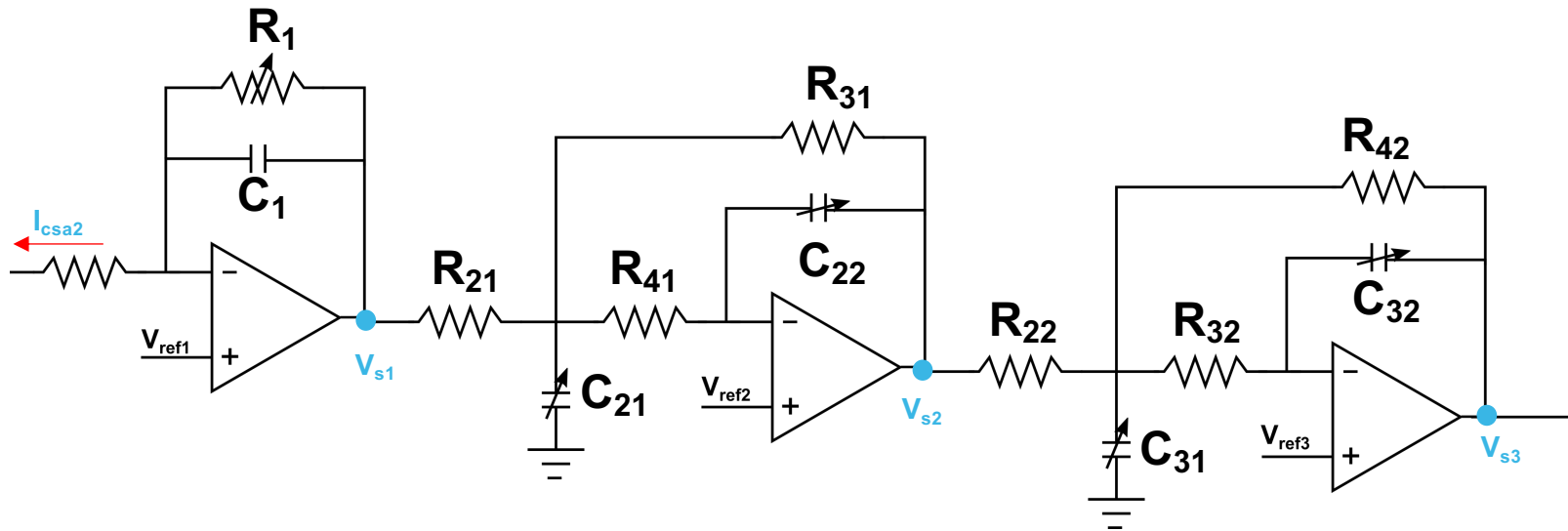


CSA₂ reset current subtraction



- Reset Quiescent Current (RQI) subtraction for CSA₂ to be implemented in CHAMPS
- Prevents propagation of leakage current and corresponding baseline shift
- To be made programmable (2-3 bits) with digital assistance independently for each channel
- Suitable for applications that have high leakage current and involve DC coupling

Shaper design



- Implemented shaper is a 5th order semi-gaussian filter with complex conjugate poles
- V_{csa2} output is a fast pulse, poses stringent requirements on peak capturing circuit (must be fast and accurate)
- Shaper slows down the variations near signal peak
- (Nearly) equal rise and fall times maximize the output signal amplitude for a given pulse duration

$$V_{s1}(s) = I_{csa2}(s) \frac{R_1}{(1 + sC_1R_1)}$$

$$V_{s2}(s) = V_{s1}(s) \frac{1}{s^2 + s \left(\frac{1}{R_{21}C_{21}} + \frac{1}{R_{31}C_{31}} + \frac{1}{R_{41}C_{21}} \right) + \frac{1}{R_{31}R_{41}C_{21}C_{31}}}$$

$V_{s3}(s)$ is similar.....

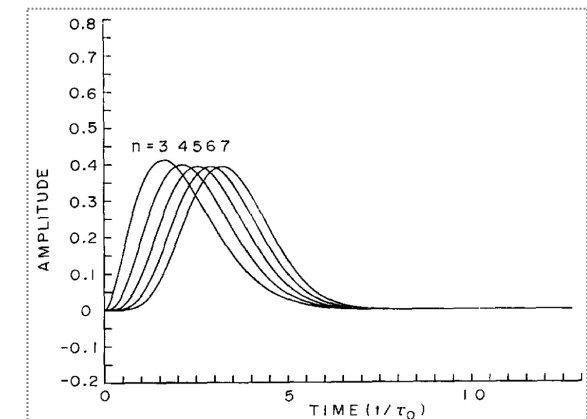


Fig. 3. Impulse responses of the Gaussian filters.

Noise minimization strategy

$$ENC^2 = (C_d + C_{in})^2 \left(A_w v_n^2 \frac{1}{T_p} + A_f K_f \right) + A_p i_n^2 T_p$$

(Sum of **white series noise**, **1/f series noise** and **parallel noise** components)

Input stage transistors for A_1 implemented using thick oxide (2.5 V) devices in 65 nm to limit leakage current and associated **parallel noise**

$$ENC_f^2 = K_f \frac{(C_d + C_g)^2}{C_g} N_f \Rightarrow C_g = C_d$$

$$ENC_w^2 = 4k_B T n \gamma \alpha_w \frac{(C_d + C_g)^2}{g_m(C_g)} N_f \Rightarrow C_g = \frac{1}{3} C_d$$

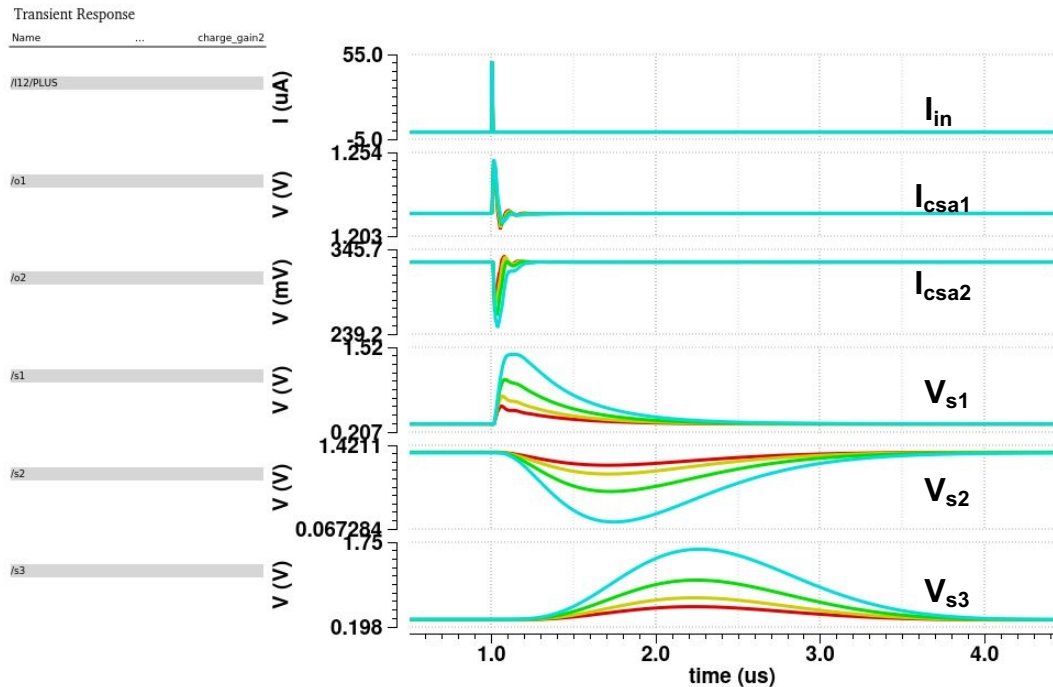
Input stage transistor sized to have $C_g \sim 40$ pF, optimal choice for minimizing noise with $C_{det} \sim 150$ pF with given power budget

	Minimum allowable transistor length	Input transistor length	Input transistor width
180 nm	180 nm	270 nm	20 mm
65 nm	280 nm	400 nm	24 mm

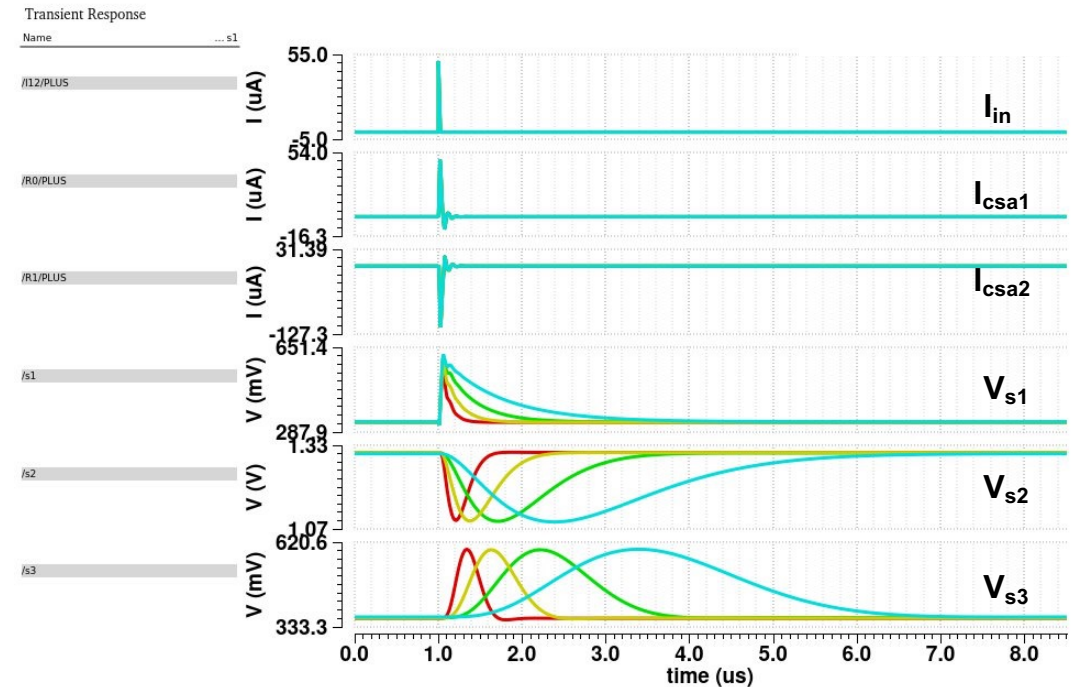
Noise in 65 nm (simulated) about 10 % lower than 180 nm

Transient responses

Variable charge gain (3, 5, 9, 16)

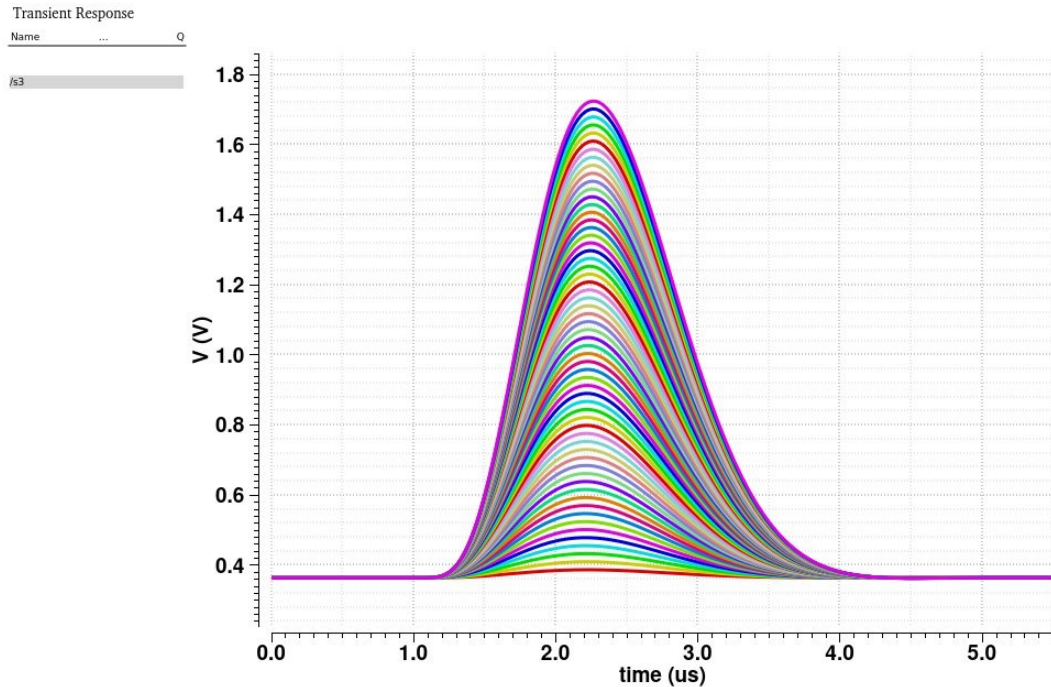


Variable peaking time (250 ns, 500 ns, 1 μ s, 2 μ s)

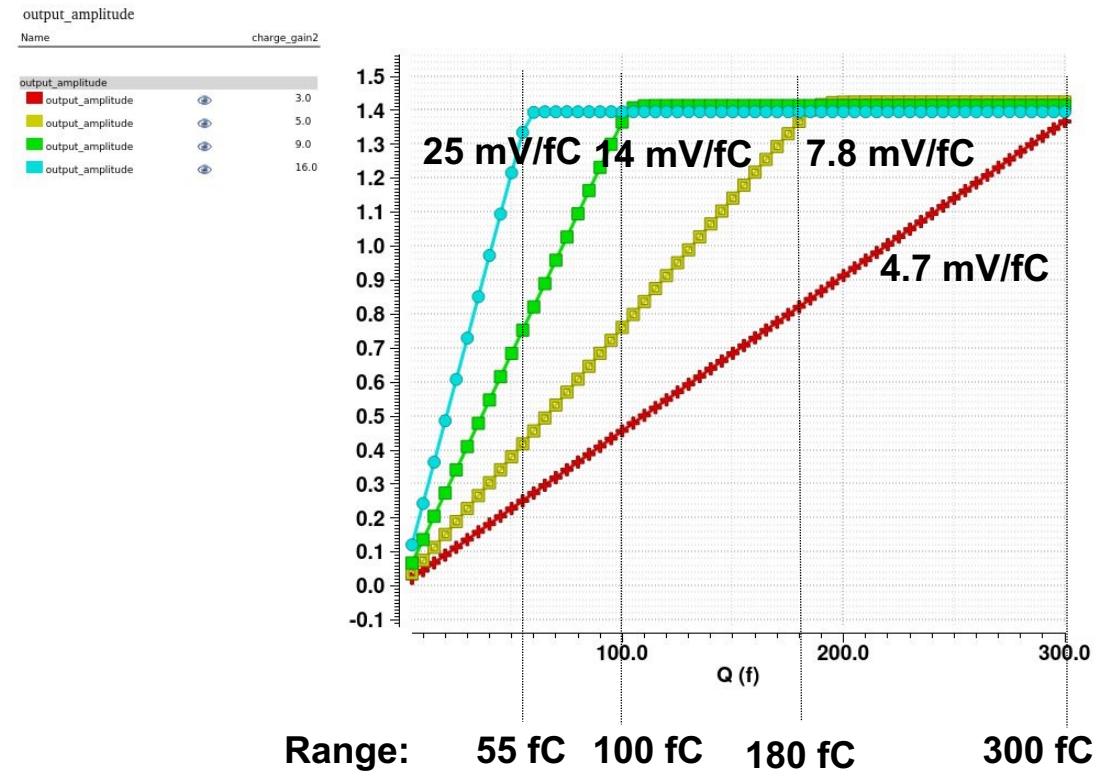


Linearity characteristics

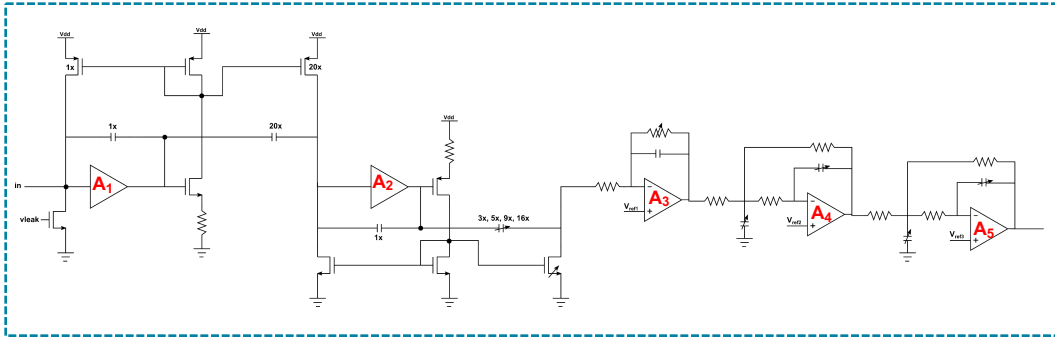
Shaper response for charge gain = 3, $T_p = 1 \mu\text{s}$



Output amplitude Vs. input charge

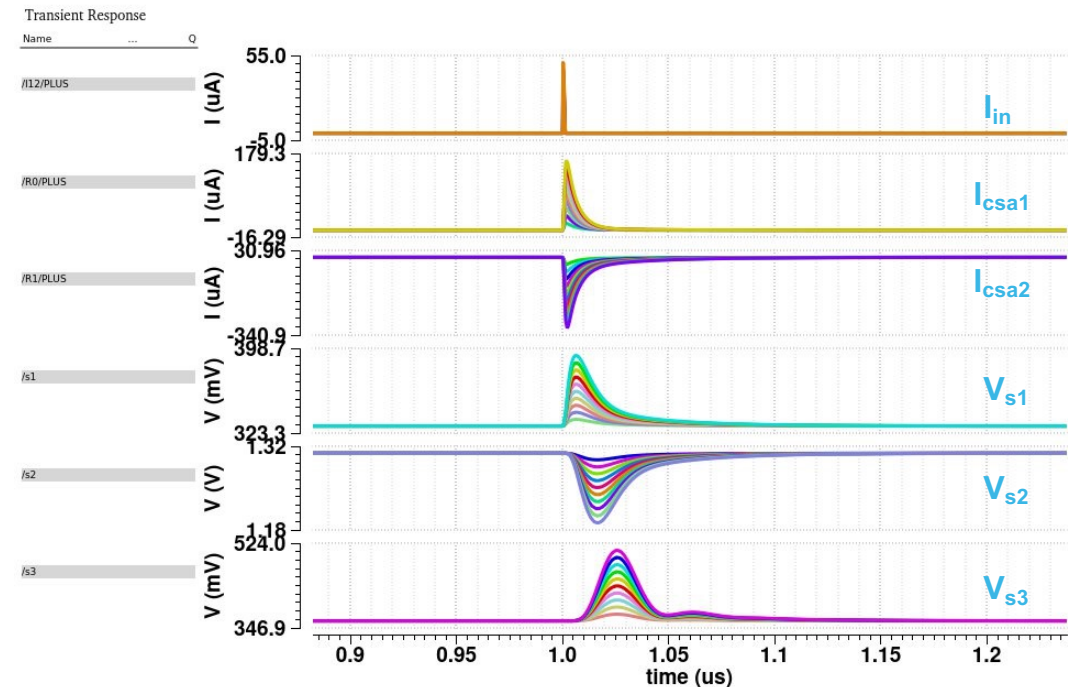


Plan for CHAMPS10 ($10 \text{ ns} \leq T_p \leq 250 \text{ ns}$)



Transient response for variable input charge (50 fC – 300 fC) with A_1 , A_2 , A_3 modeled as ideal VCVS

- Limited bandwidth of A_1 and A_2 disallows shaping times $< 250 \text{ ns}$
- Currently, amplifiers A_1 and A_2 implemented as 3-stage amplifiers
- Difficult to achieve higher bandwidth without sacrificing stability
- CHAMPS10 will incorporate topology modification for A_1 and A_2



Thank you